

Build Up HDI (Standard)	
HDI12_1+10b+1_1,50_35_engl	12 - Layers Core: 0,10 mm Cu 35/35 µm
WE-Article No.:	1 + 10B + 1
Customer:	



layer description		configuration
Customer	WE	
	TOP/VS	
	2	
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	BOT/RS	

Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
			[µm]	[µm]
Foil	12 µm ¹⁾		12	
		1 x 1080	60	
Foil	9 µm		30	
		2 x 1080	133	
	35 µm		33	
0,100 mm			100	
	35 µm		33	
		2 x 1080	124	
	35 µm		33	
0,100 mm			100	
	35 µm		33	
		2 x 1080	124	
	35 µm		33	
0,100 mm			100	
	35 µm		33	
		2 x 1080	133	
Foil	9 µm		30	
		1 x 1080	60	
Foil	12 µm ¹⁾		12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1506
Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	1,50	+/-	0,12	mm			Date:	Engineer:
thickness with electro plated Cu:	1,59	+/-	0,15	mm				
total thickness with soldermask	1,65	+/-	0,17	mm				
customer requirement		+/-		mm	point:			
prepared: on 29.03.2006	by S. Keller	checked: on 04.05.2006	by M.Kress	approved: on 04.05.2006	by R.Schönholz	revision 00	page: 10+	